

ABSTRACT

The object of the invention is to provide a polishing pad capable of maintaining high-precision end-point optical detection over a long period from the start of use to the end of use even if 5 polishing is performed with an alkaline or acid slurry, as well as a method of manufacturing a semiconductor device with this polishing pad. The polishing pad of the invention is used in chemical mechanical polishing and has a polishing region and a light-transmitting region, wherein the light-transmitting region 10 satisfies that the difference ΔT ($\Delta T = T_0 - T_1$) (%) between T_0 and T_1 is within 10 (%) over the whole range of measurement wavelengths of from 400 to 700 nm, wherein T_1 is the light transmittance (%) of the light-transmitting region measured at the measurement wavelength λ after dipping for 24 hours in a KOH aqueous solution 15 at pH 11 or an H_2O_2 aqueous solution at pH 4 and T_0 is the light-transmittance (%) measured at the measurement wavelength λ before the dipping.